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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HD74HCT138

3-to-8-line Decoder/Demultiplexer



ADE-205-547 (Z)
1st. Edition
Sep. 2000

Description

The HD74HCT138 has 3 binary select inputs (A, B, and C). If the device is enabled these inputs determine which one of the eight normally high outputs will go low. Two active low and one active high enables (G_1 , G_{2A} and G_{2B}) are provided to ease the cascading of decoders.

Features

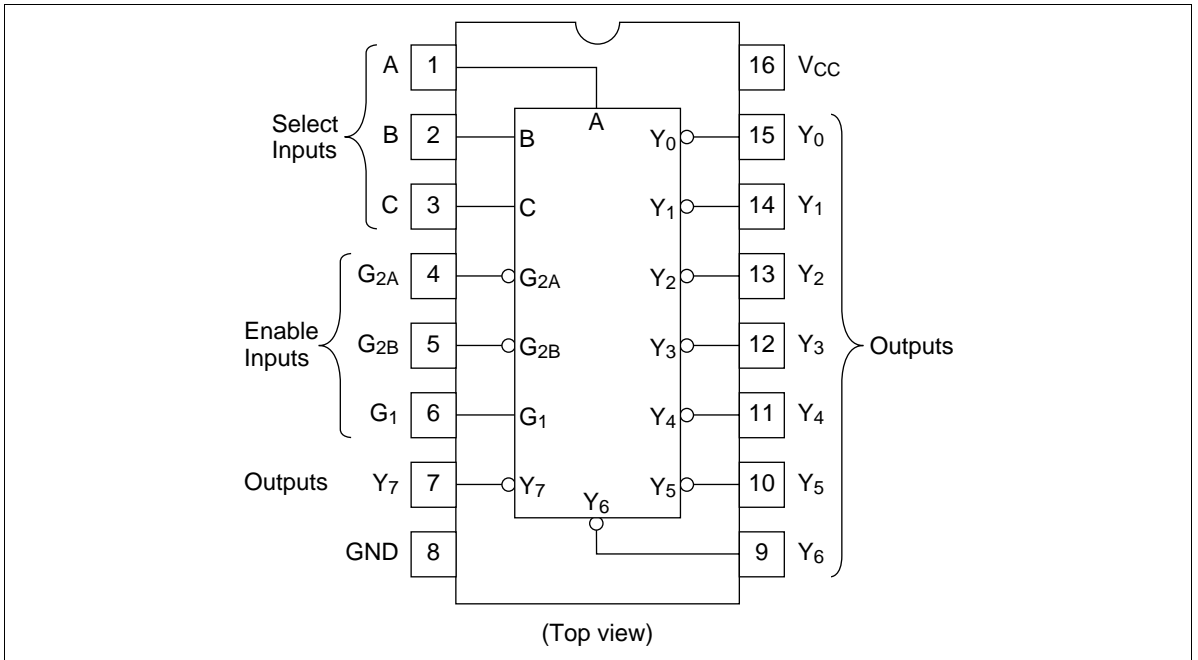
- LSTTL Output Logic Level Compatibility as well as CMOS Output Compatibility
- High Speed Operation: t_{pd} (A, B, C to Y) = 18.5 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 4.5$ to 5.5 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)

Function Table

Inputs

Enable			Select			Outputs							
G_1	G_{2A}	G_{2B}	C	B	A	Y_0	Y_1	Y_2	Y_3	Y_4	Y_5	Y_6	Y_7
X	X	H	X	X	X	H	H	H	H	H	H	H	H
X	H	X	X	X	X	H	H	H	H	H	H	H	H
L	X	X	X	X	X	H	H	H	H	H	H	H	H
H	L	L	L	L	L	L	H	H	H	H	H	H	H
H	L	L	L	L	H	H	L	H	H	H	H	H	H
H	L	L	L	H	L	H	H	L	H	H	H	H	H
H	L	L	L	H	H	H	H	H	L	H	H	H	H
H	L	L	H	L	L	H	H	H	H	L	H	H	H
H	L	L	H	L	H	H	H	H	H	H	L	H	H
H	L	L	H	H	L	H	H	H	H	H	H	L	H
H	L	L	H	H	H	H	H	H	H	H	H	H	L

Pin Arrangement



DC Characteristics

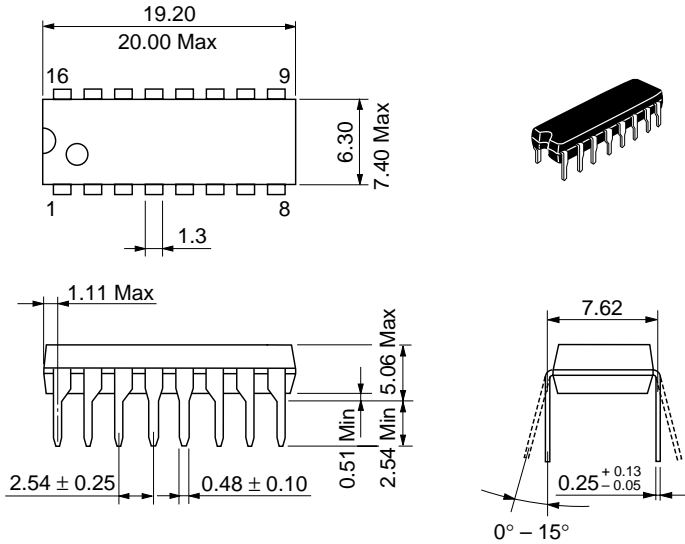
Item	Symbol	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions		
		Min	Typ	Max	Min		Max	V _{CC} (V)	
Input voltage	V _{IH}	2.0	—	—	2.0	—	V	4.5 to 5.5	
	V _{IL}	—	—	0.8	—	0.8	V	4.5 to 5.5	
Output voltage	V _{OH}	4.4	—	—	4.4	—	V	4.5	Vin = V _{IH} or V _{IL} I _{OH} = -20 μA
		4.18	—	—	4.13	—		4.5	I _{OH} = -4 mA
	V _{OL}	—	—	0.1	—	0.1	V	4.5	Vin = V _{IH} or V _{IL} I _{OL} = 20 μA
		—	—	0.26	—	0.33		4.5	I _{OL} = 4 mA
Input current	I _{in}	—	—	±0.1	—	±1.0	μA	5.5	Vin = V _{CC} or GND
Quiescent supply current	I _{CC}	—	—	4.0	—	40	μA	5.5	Vin = V _{CC} or GND, I _{out} = 0 μA

AC Characteristics (C_L = 50 pF, Input t_r = t_f = 6 ns)

Item	Symbol	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions		
		Min	Typ	Max	Min		Max	V _{CC} (V)	
Propagation delay time	t _{PHL}	—	18	35	—	44	ns	4.5	A, B or C to output
	t _{PLH}	—	19	30	—	38	ns	4.5	
	t _{PHL}	—	17	30	—	38	ns	4.5	G ₁ to output
	t _{PLH}	—	17	30	—	38	ns	4.5	
	t _{PHL}	—	17	35	—	44	ns	4.5	G _{2A} or G _{2B} to output
	t _{PLH}	—	17	30	—	38	ns	4.5	
Output rise/fall time	t _{TLH} t _{THL}	—	5	15	—	19	ns	4.5	
Input capacitance	C _{in}	—	5	10	—	10	pF	—	

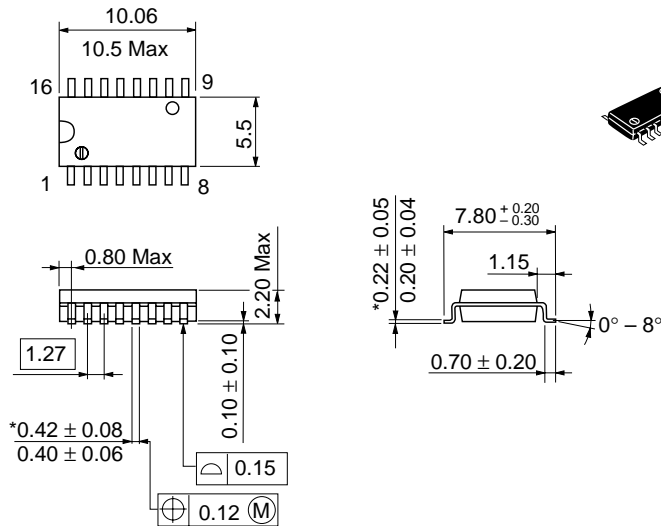
Package Dimensions

Unit: mm



Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	1.07 g

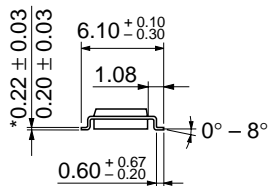
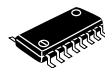
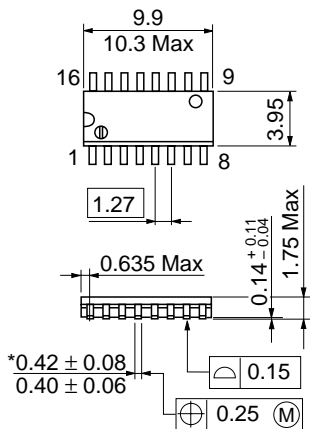
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.24 g

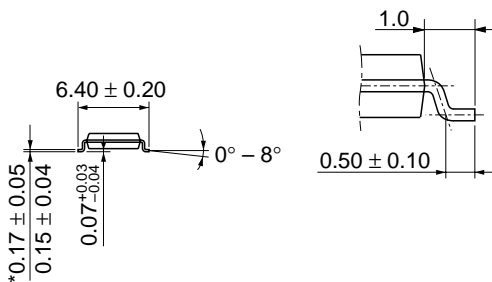
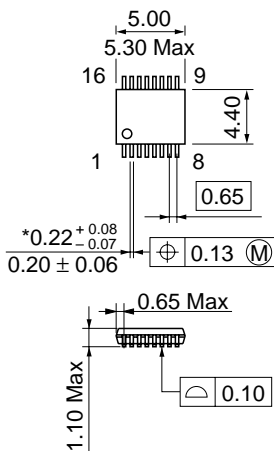
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.15 g

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	TTP-16DA
JEDEC	—
EIAJ	—
Mass (reference value)	0.05 g

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HITACHI

Hitachi, Ltd.

Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL NorthAmerica : <http://semiconductor.hitachi.com/>
 Europe : <http://www.hitachi-eu.com/hel/ecg>
 Asia : <http://sicapac.hitachi-asia.com>
 Japan : <http://www.hitachi.co.jp/Sicd/indx.htm>

For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive,
San Jose, CA 95134
Tel: <1> (408) 433-1990
Fax: <1> (408) 433-0223

Hitachi Europe GmbH
Electronic Components Group
Dornacher Straße 3
D-85622 Feldkirchen, Munich
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.
Electronic Components Group.
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 585160

Hitachi Asia Ltd.
Hitachi Tower
16 Collyer Quay #20-00,
Singapore 049318
Tel : <65>-538-6533/538-8577
Fax : <65>-538-6933/538-3877
URL : <http://www.hitachi.com.sg>

Hitachi Asia Ltd.
(Taipei Branch Office)
4/F, No. 167, Tun Hwa North Road,
Hung-Kuo Building,
Taipei (105), Taiwan
Tel : <886>-(2)-2718-3666
Fax : <886>-(2)-2718-8180
Telex : 23222 HAS-TP
URL : <http://www.hitachi.com.tw>

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower,
World Finance Centre,
Harbour City, Canton Road
Tsim Sha Tsui, Kowloon,
Hong Kong
Tel : <852>-(2)-735-9218
Fax : <852>-(2)-730-0281
URL : <http://www.hitachi.com.hk>

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